TP500-H60-SF

AOK-TDS-166 Ver:A0

Silicon-free Thermally Conductive Gap Filler Pad

TP500-H60-SF is a silicon-free thermally conductive gap filler pad for high electrical insulation ,excellent thermal conductivity and electrical insulation. It can work stably at -40°C~125°C and meet UL94 V-0 flame retardant grade.

Features

- 5.0 W/(m·K)
- No Silicone Oil Exudation or Siloxane Evaporation
- Good Mechanical Properties
- High compression
- Naturally tacky on both sides
- High Electrical Insulation
- Excellent Durability

Typical Applications

- Fiber Optic Modules
- Medical Equipment
- Hard Disk Drives (HDDs)
- Optical Precision Equipment
- High-end Industrial Control Equipment
- Silicone-Sensitive Components/Devices/Products
- Automotive Sensors/Control Modules

Typical Properties

Properties	Attribute	Test Method
Color	Blue	Visual
Thickness (mm)	0.5 to 3.0	ASTM D374
Density (g/cc)	3.1	ASTM D792
Hardness (Shore 00)	60	ASTM D2240
Weight Loss (%)	⩽1.0	Filter paper adsorption @25%compression/125°C/48h
Flammability	V-0	UL 94
Usage Temperature (°C)	- 40 to 125	/
Shelf Life (month)	12	Temperature <40°C avoid extrusion and exposure to the sun
Electrical		
Breakdown Voltage (kV/mm)	⩾6.0	ASTM D149
Volume Resistivity (Ω·cm)	10^{10}	ASTM D257
Dielectric Constant	5.7	ASTM D150
Thermal		
Thermal Conductivity (W/(m·K))	5.0	ISO 22007-2

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